



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-04-07
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	N7BB*MV7SABB	A	Z7GA	2016-04-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	14.0	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	nickel/Palladium/Gold (Ni/Pd/Au), ENE	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LGA	2.5x3x0.86	14	No lead	
Comment	Package: A037 VFLGA 2.5X3X0.86 14L; MDF valid for LSM6DS3TR			

QueryList : ROHS directive 2011/65/EU _ANNEX IV	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	N78B*MV7SABB									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	6.846	mg	supplier	die	Silicon (Si)	7440-21-3		6.359	mg	928864	454214				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.018	mg	2629	1286				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.022	mg	3214	1571				
				supplier	metallisation	Cobalt (Co)	7440-48-4		0.013	mg	1899	929				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.005	mg	730	357				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.007	mg	1022	500				
				supplier	metallisation	Tungsten (W)	7440-33-7		0.002	mg	292	143				
				supplier	metallisation	Zirconium (Zr)	7440-67-7		0.002	mg	292	143				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.012	mg	1753	857				
				supplier	passivation	Silicon Oxide	7631-86-9		0.087	mg	12708	6214				
					JIG - R	die glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electron	0.319	mg	46597	22786			
				substrate	Other Organic Materials	1.772	mg	supplier	prepreg	Fiber glass	65997-17-3		0.248	mg	142711	17714
								supplier	prepreg	epoxy resin	28906-96-9		0.158	mg	90921	11286
supplier	prepreg	Calcium carbonate	471-34-1						0.023	mg	13235	1643				
supplier	prepreg	Calcium oxide	1305-78-8						0.023	mg	13235	1643				
supplier	Solder mask	Acrylic resin	9003-01-4						0.192	mg	110486	13714				
supplier	Solder mask	Epoxy resin	29690-82-2						0.077	mg	44310	5500				
supplier	Solder mask	Barium sulfate	7727-43-7						0.056	mg	32225	4000				
supplier	Solder mask	Silica, vitreous	60676-86-0						0.019	mg	10934	1357				
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.011	mg	6330	786				
supplier	Solder mask	aromatic carbonyl compound	Proprietary						0.015	mg	8632	1071				
supplier	Solder mask	amine compound	Proprietary						0.002	mg	1151	143				
supplier	Solder mask	Phtalocyanine blue	147-14-8						0.001	mg	575	71				
supplier	metallisation	Copper (Cu)	7440-50-8						0.894	mg	514306	63839				
	Nickel (Ni)	supplier	metallisation					Nickel (Ni)	7440-02-0		0.016	mg	9063	1125		
	Precious metals	supplier	metallisation					Gold (Au)	7440-57-5		0.002	mg	1230	153		
	Precious metals	supplier	metallisation					Palladium (Pd)	7440-05-3		0.001	mg	656	81		
Die attach	Other inorganic materials	0.202	mg					supplier	tape	epoxy resin	Proprietary		0.128	mg	633663	9143
				supplier	tape	polyolefin	9003-07-0		0.064	mg	316832	4571				
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.010	mg	49505	714				
Die attach 2	Other inorganic materials	0.205	mg	supplier	tape	amorphous silica	7631-86-9		0.086	mg	419512	6143				
				supplier	tape	epoxy resin	25038-59-9		0.051	mg	248780	3643				
				supplier	tape	Acrylic resin	9003-01-4		0.034	mg	165854	2429				
				supplier	tape	Epoxyde Bisphenol A Resin	25068-38-6		0.034	mg	165854	2429				
Bonding wire	Precious metals	0.276	mg	supplier	wire	Gold (Au)	7440-57-5		0.273	mg	989130	19500				
				supplier	wire	Copper (Cu)	7440-50-8		0.002	mg	7246	143				
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	3623	71				
encapsulation	Other Organic Materials	4.733	mg	supplier	mold compound	Silica, vitreous	60676-86-0		3.763	mg	795056	268786				
				supplier	mold compound	Silica	7631-86-9		0.473	mg	99937	33786				
				supplier	mold compound	Epoxy Resin	Proprietary		0.189	mg	39932	13500				
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.166	mg	35073	11857				
				supplier	mold compound	Phenol Resin	Proprietary		0.118	mg	24931	8429				
				supplier	mold compound	Carbon black	1333-86-4		0.024	mg	5071	1714				